

Product Specification

Product:	Dielectric Paste
Part Number:	07MTGT40

Application Scope :

The paste is suitable for thick film circuit filling and bonding, and can be used on ceramic, glass, metal and other substrates.

Usage Conditions :

Substrate	Thick-film circuit, alumina ceramic, ceramic, glass, metal
Usage Method	Lattice printing
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (if the baking temperature is below 300°C, the baking time may be adjusted according to actual conditions).
Firing Condition	The sintering temperature is 550±10°C (recommended value) and the sintering time is 10~30 minutes. The sintering range can be adjusted between 420-800°C as needed, but the peak temperature must be maintained for at least 10 minutes.
Thinner	ST-1001

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤8μm	FOG test
2	Viscosity	350~500Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor SC4-14/6R), 10 rpm, 25±1°C
3	Appearance	Achromatic colour,Transparent	

2. Characteristics After Curing :

Under the condition of 1 sintering, Check fired film produced under the conditions specified in 1)

Characteristics		Standard	Test Method And Conditions
4	Appearance	Compact and dense	Visual inspection & microscopy

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.